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Semiconductor devices - Mechanical and climatic test methods - Part 3: External visual examination

Táto norma obsahuje anglickú verziu európskej normy.
This standard includes the English version of the European Standard.

Táto norma bola oznámená vo Vestníku ÚNMS SR č. 09/17

Obsahuje: EN 60749-3:2017, IEC 60749-3:2017

Oznámením tejto normy sa od 07.04.2020 ruší
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Úrad pre normalizáciu, metrológiu a skúšobníctvo Slovenskej republiky, 2017
Podľa zákona č. 264/1999 Z. z. o technických požiadavkách na výrobky a o posudzovaní zhody a o zmene a doplnení niektorých zákonov v znení neskorších predpisov sa slovenská technická norma a časti slovenskej technickej normy môžu rozmnožovať alebo rozširovať len so súhlasom slovenského národného normalizačného orgánu.

EUROPEAN STANDARD
NORME EUROPÉENNE
EUROPÄISCHE NORM

EN 60749-3

June 2017

ICS 31.080.01

Supersedes EN 60749-3:2002

English Version

Semiconductor devices - Mechanical and climatic test methods -
Part 3: External visual examination
(IEC 60749-3:2017)

Dispositifs à semiconducteurs - Méthodes d'essais
mécaniques et climatiques - Partie 3: Examen visuel
externe
(IEC 60749-3:2017)

Halbleiterbauelemente - Mechanische und klimatische
Prüfverfahren - Teil 3: Äußere Sichtprüfung
(IEC 60749-3:2017)

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European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

CEN-CENELEC Management Centre: Avenue Marnix 17, B-1000 Brussels

European foreword

The text of document 47/2345/FDIS, future edition 2 of IEC 60749-3, prepared by IEC/TC 47 "Semiconductor devices" was submitted to the IEC-CENELEC parallel vote and approved by CENELEC as EN 60749-3:2017.

The following dates are fixed:

- latest date by which the document has to be implemented at national level by publication of an identical national standard or by endorsement (dop) 2018-01-07
- latest date by which the national standards conflicting with the document have to be withdrawn (dow) 2020-04-07

This document supersedes EN 60749-3:2002.

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Endorsement notice

The text of the International Standard IEC 60749-3:2017 was approved by CENELEC as a European Standard without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated :

IEC 60749-9	NOTE	Harmonized as EN 60749-9.
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Annex ZA

(normative)

Normative references to international publications with their corresponding European publications

The following documents, in whole or in part, are normatively referenced in this document and are indispensable for its application. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE 1 When an International Publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

NOTE 2 Up-to-date information on the latest versions of the European Standards listed in this annex is available here: www.cenelec.eu.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61340-5-1	-	Electrostatics - Part 5-1: Protection of electronic devices from electrostatic phenomena - General requirements	EN 61340-5-1	-
IEC 62483	-	Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semiconductor devices	-	-



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Edition 2.0 2017-03

INTERNATIONAL STANDARD

**Semiconductor devices – Mechanical and climatic test methods –
Part 3: External visual examination**



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IEC 60749-3

Edition 2.0 2017-03

INTERNATIONAL STANDARD

**Semiconductor devices – Mechanical and climatic test methods –
Part 3: External visual examination**

INTERNATIONAL
ELECTROTECHNICAL
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

**SEMICONDUCTOR DEVICES –
MECHANICAL AND CLIMATIC TEST METHODS –****Part 3: External visual examination****FOREWORD**

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International Standard IEC 60749-3 has been prepared by IEC technical committee 47: Semiconductor devices.

This second edition cancels and replaces the first edition published in 2002. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) reference to the need for ESD protection;
- b) inclusion of information on the phenomenon of tin whiskers;
- c) inclusion of an optional report form/checklist.

The text of this standard is based on the following documents:

FDIS	Report on voting
47/2345/FDIS	47/2370/RVD

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 60749 series, published under the general title *Semiconductor devices – Mechanical and climatic test methods*, can be found on the IEC website.

The committee has decided that the contents of this document will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific document. At this date, the document will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

SEMICONDUCTOR DEVICES – MECHANICAL AND CLIMATIC TEST METHODS –

Part 3: External visual examination

1 Scope

The purpose of this part of IEC 60749 is to verify that the materials, design, construction, markings, and workmanship of a semiconductor device are in accordance with the applicable procurement document. External visual inspection is a non-destructive test and applicable for all package types. The test is useful for qualification, process monitor, or lot acceptance.

2 Normative references

The following documents are referred to in the text in such a way that some or all of their content constitutes requirements of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61340-5-1, *Electrostatics – Part 5-1: Protection of electronic devices from electrostatic phenomena – General requirements*

IEC 62483, *Environmental acceptance requirements for tin whisker susceptibility of tin and tin alloy surface finishes on semiconductor devices*

koniec náhľadu – text ďalej pokračuje v platenej verzii STN